# **<u>MOSFET</u>** – Power, Single N-Channel 40 V, 0.67 mΩ, 370 A

#### Features

- Small Footprint (5x6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- NVMFS5C404NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

	( 0		,			
Parameter			Symbol	Value	Unit	
Drain-to-Source Voltage			V <sub>DSS</sub>	40	V	
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V	
Continuous Drain	Steady	T <sub>C</sub> = 25°C	I <sub>D</sub>	370	А	
Current R <sub>θJC</sub> (Notes 1, 3)		T <sub>C</sub> = 100°C		260		
Power Dissipation	State	T <sub>C</sub> = 25°C	PD	200	W	
R <sub>θJC</sub> (Note 1)		$T_{C} = 100^{\circ}C$		100		
Continuous Drain	Steady State	T <sub>A</sub> = 25°C	I <sub>D</sub>	52	А	
Current R <sub>θJA</sub> (Notes 1, 2, 3)		$T_A = 100^{\circ}C$		37		
Power Dissipation		T <sub>A</sub> = 25°C	PD	3.9	W	
$R_{\theta JA}$ (Notes 1 & 2)		T <sub>A</sub> = 100°C		1.9		
Pulsed Drain Current	T <sub>A</sub> = 25	°C, t <sub>p</sub> = 10 μs	I <sub>DM</sub>	900	А	
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>stg</sub>	–55 to + 175	°C	
Source Current (Body Diode)			ا <sub>S</sub>	191	А	
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 38 A)			E <sub>AS</sub>	907	mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C	

MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	0.75	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	39	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.

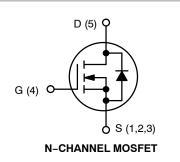
3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

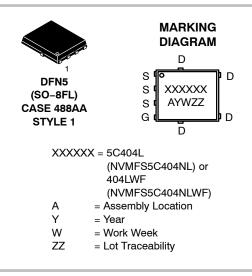


## **ON Semiconductor®**

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V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
40 V	$0.67~\mathrm{m}\Omega\ensuremath{@}10~\mathrm{V}$	070 4
40 V	1.0 mΩ @ 4.5 V	370 A





#### **ORDERING INFORMATION**

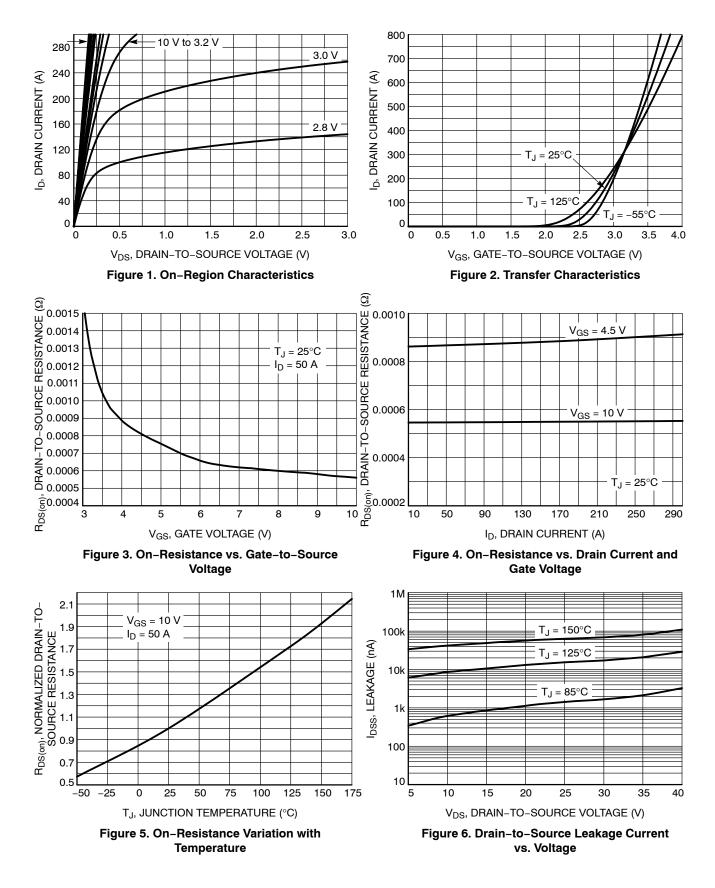
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}C$ unless otherwise specified)

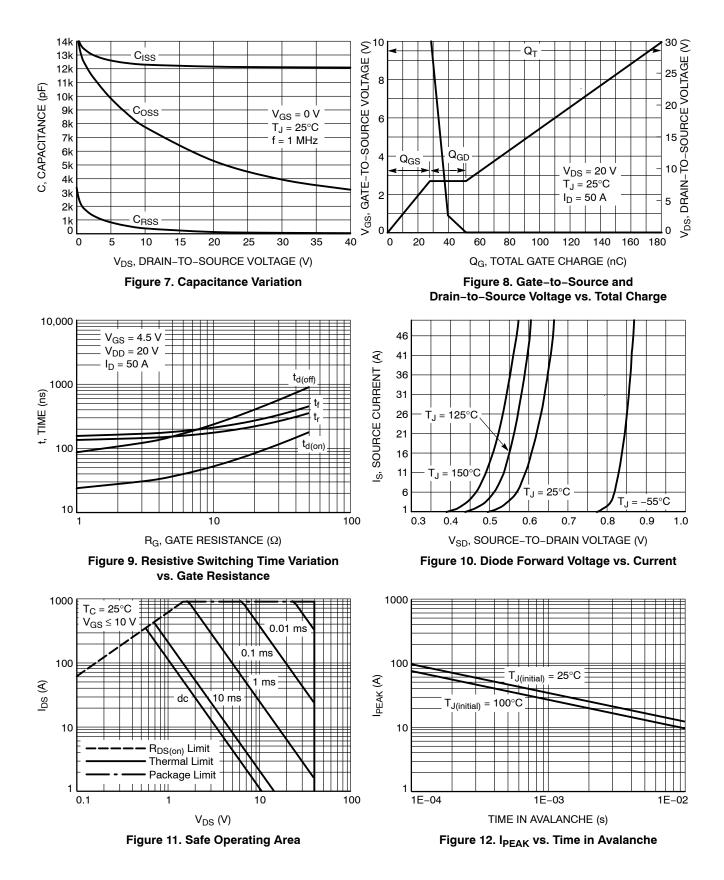
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS								
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		40			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> / T <sub>J</sub>				21.6		mV/°C	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25 °C			10		
		V <sub>DS</sub> = 40 V	T <sub>J</sub> = 125°C			250	250 μA	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = 20 V				100	nA	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS}$ = $V_{DS}$ , $I_D$ = 250 $\mu$ A		1.2		2.0	V	
Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				-6.2		mV/°C	
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 50 A		0.52	0.67		
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 50 A		0.75	1.0	mΩ	
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> =15 V, I <sub>I</sub>	<sub>0</sub> = 50 A		270		S	
CHARGES, CAPACITANCES & GATE RE	SISTANCE							
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 25 V			12168			
Output Capacitance	C <sub>OSS</sub>				4538		pF	
Reverse Transfer Capacitance	C <sub>RSS</sub>				79.8			
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS}$ = 4.5 V, $V_{DS}$ = 20 V; $I_{D}$ = 50 A			81			
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 20 V; $I_{D}$ = 50 A			181		1	
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 20 V; I <sub>D</sub> = 50 A			8.5		nC	
Gate-to-Source Charge	Q <sub>GS</sub>				27.8		-	
Gate-to-Drain Charge	Q <sub>GD</sub>				23.8			
Plateau Voltage	V <sub>GP</sub>				2.7		V	
SWITCHING CHARACTERISTICS (Note 5	5)							
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS}$ = 4.5 V, $V_{DS}$ = 20 V, $I_{D}$ = 50 A, $R_{G}$ = 1.0 $\Omega$			24		- ns	
Rise Time	t <sub>r</sub>				135			
Turn-Off Delay Time	t <sub>d(OFF)</sub>				87			
Fall Time	t <sub>f</sub>				157			
DRAIN-SOURCE DIODE CHARACTERIS	TICS							
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 50 A	$T_J = 25^{\circ}C$		0.7	1.2		
			T <sub>J</sub> = 125°C		0.61		V	
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, dIS/dt = 100 A/µs, I <sub>S</sub> = 50 A			97.4			
Charge Time	ta				46.5		ns	
Discharge Time	t <sub>b</sub>				50.9		1	
Reverse Recovery Charge	Q <sub>RR</sub>				190		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width  $\leq 300 \ \mu$ s, duty cycle  $\leq 2\%$ . 5. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**



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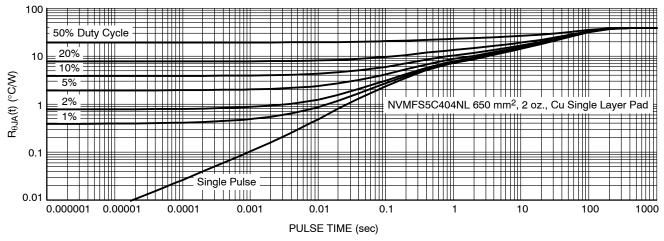


Figure 13. Thermal Characteristics

#### **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NVMFS5C404NLT1G	5C404L	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5C404NLWFT1G	404LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel
NVMFS5C404NLT3G	5C404L	DFN5 (Pb–Free)	5000 / Tape & Reel
NVMFS5C404NLWFT3G	404LWF	DFN5 (Pb-Free, Wettable Flanks)	5000 / Tape & Reel
NVMFS5C404NLAFT1G	5C404L	DFN5 (Pb–Free)	1500 / Tape & Reel
NVMFS5C404NLWFAFT1G	404LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





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